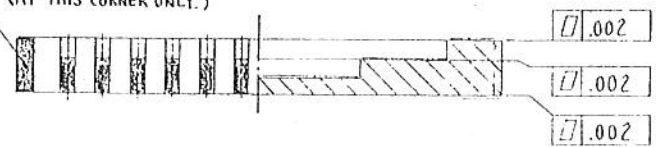


EDGE METALLIZATION
(AT THIS CORNER ONLY.)



- NOTE: 1. ALL EXPOSED METALLIZATION SHALL BE PLATED WITH 80~150μ INCHES ELECTROLYTIC NICKEL AND THEN WITH 60μ INCHES MIN. ELECTROLYTIC GOLD.
 2. DIE ATTACH PAD AND SEAL RING ISOLATED.
 3. No.1 PAD TO BE ELECTRICALLY CONNECTED TO THE HEAT SINK PAD.



ISSUE	NEW DRAWING	FEB-13-85	5546/010
DESCRIPTION		DATE	DRAWN
REVISIONS			

UNLESS OTHERWISE SPECIFIED TOLERANCES	DR-WFI	NGK SPARK PLUG CO., LTD	
	K.Sato	JAN-26-83	NAGOYA JAPAN.
MATERIAL	CHECKED	INTK TECHNICAL CERAMIC DIVISION	
	APPROVED	TITLE	
BLACK ALUMINA	UNO	INCH	48LEAD CHIP CARRIER
	SCHE		OWG NO.
			ISSUE
			1RK48F1-185B